

N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

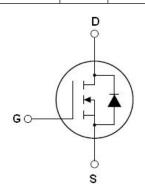
Features

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- ●Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V _{DS min@Tjmax}	710	V
R _{DS(ON)TYP}	680	mΩ
ID	6	Α
Qg	7.2	nC



Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65N760K	TO-252-2L	NCE65N760K



TO-252

Table 1. Absolute Maximum Ratings (T_c=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	V _{DS}	650	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) DC	V _G s	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	6	Α
Continuous Drain Current at Tc=100°C	I _{D (DC)}	4.2	Α
Pulsed drain current (Note 1)	I _{DM (pluse)}	24	А
Maximum Power Dissipation(Tc=25°C)	P _D	73	W
Derate above 25°C		0.49	W/°C
Avalanche current ^(Note 2)	I _{AS}	2	А
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55+175	°C

^{*} limited by maximum junction temperature



Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	2.05	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

 Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±200	nA
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =250µA	3	3.5	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =3A		680	790	mΩ
Dynamic Characteristics						
Input Capacitance	C _{lss}	\/ -50\/\/ -0\/		461		pF
Output Capacitance	Coss	V_{DS} =50V, V_{GS} =0V,		14		pF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz		4		pF
Total Gate Charge	Qg			7.2		nC
Gate-Source Charge	Q _{gs}	V_{DS} =480 V , I_{D} =3 A ,		1.3		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V		1.3		nC
Gate plateau voltage	Vgp			5.2		V
Intrinsic gate resistance	R _G	f = 1 MHz open drain		35		Ω
Switching times	,					
Turn-on Delay Time	t _{d(on)}			10		nS
Turn-on Rise Time	t _r	V_{DD} =480 V , I_{D} =3 A ,		7		nS
Turn-Off Delay Time	t _{d(off)}	$R_G=1.7\Omega, V_{GS}=10V$		55		nS
Turn-Off Fall Time	t _f			8		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T 0500			6	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			24	Α
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =6A,V _{GS} =0V		0.9	1.2	V
Reverse Recovery Time	t _{rr}	T: 05°0 L 0A		185		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I _F =3A,		1.3		uC
Peak Reverse Recovery Current	I _{rrm}	di/dt=100A/µs		14		Α

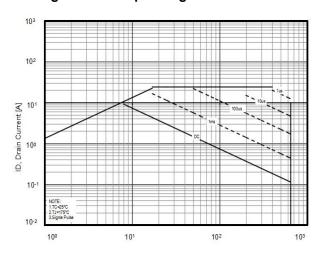
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V, RG=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area



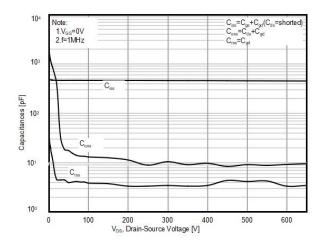


Figure 3. Transfer characteristics

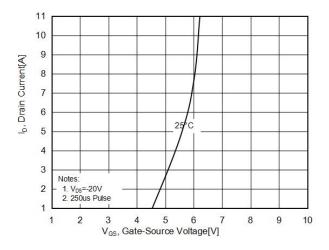


Figure 4. Output characteristics

Figure 2. Capacitance

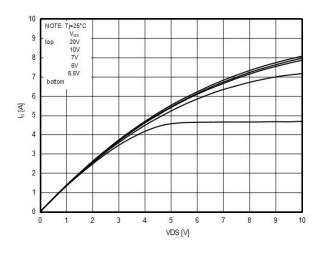


Figure 5. R_{DS(ON)} vs Junction Temperature

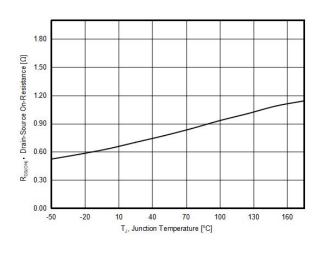


Figure 6. BV_{DSS} vs Junction Temperature

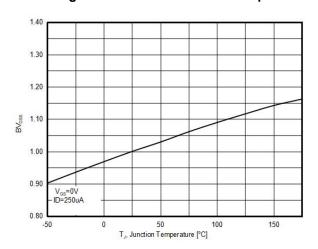




Figure 7. Maximum I_D vs Junction Temperature

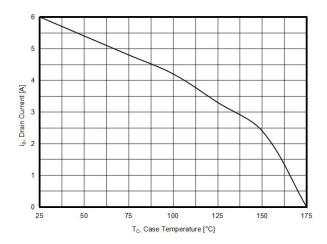


Figure 9. Static drain-source on resistance

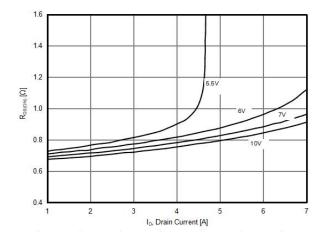


Figure 8. Gate charge waveforms

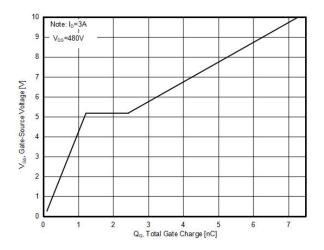
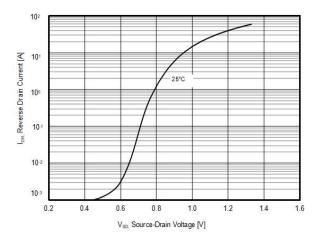


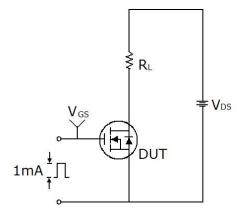
Figure 10. Source-Drain Diode Forward Voltag

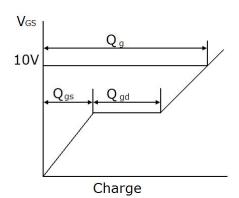




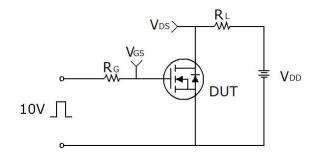
Test circuit

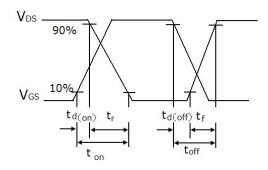
1) Gate charge test circuit & Waveform



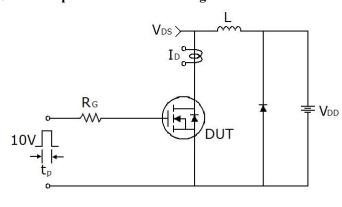


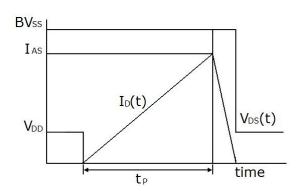
2) Switch Time Test Circuit:





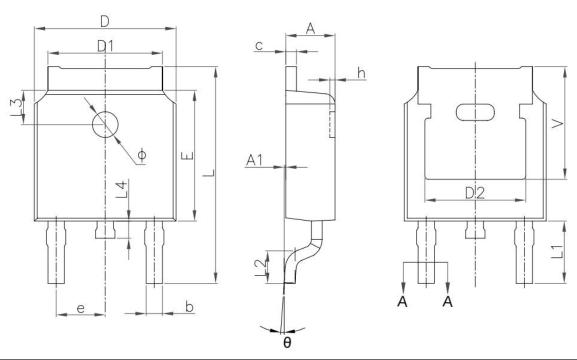
3) Unclamped Inductive Switching Test Circuit & Waveforms







TO-252-E Package Information



Symbol	Dimensions I	Dimensions In Millimeters		s In Inches		
	Min.	Max.	Min.	Max.		
Α	2.20	2.40	0.087	0.094		
A1	0.00	0.13	0.000	0.005		
b	0.66	0.86	0.026	0.033		
b1	0.73	0.79	0.029	0.031		
С	0.46	0.58	0.018	0.023		
c1	0.50	0.52	0.020	0.020		
D	6.50	6.70	0.256	0.264		
D1	5.10	5.46	0.201	0.215		
D2	4.83	4.83 REF		0.19REF		
E	6.00	6.20	0.236	0.244		
е	2.19	2.39	0.086	0.094		
L	9.80	10.40	0.386	0.409		
L1	2.90	REF	0.11	REF		
L2	1.40	1.70	0.055			
L3	1.60	1.60 REF		REF		
L4	0.60	1.00	0.024	0.039		
Ф	1.10	1.30	0.043	0.051		
θ	0°	8°	0°	8°		
h	0.00	0.30	0.000	0.012		



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